

IFW



PT-03-008

September 20, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/807,036 03/23/04 |  
Thomas Aisenbrey  
LOW COST THERMAL MANAGEMENT DEVICE  
OR HEAT SINK USING CONDUCTIVE  
PLASTICS OR CONDUCTIVE COMPOSITES  
| \_\_\_\_\_ |

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on September 21, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date SBQ 9/21/04

U.S. Patent 5,849,130 to Browne, "Method of Making and Using Thermally Conductive Joining Film," discloses a joining film composed of a thin polymeric composite sheet material containing orientated thermally conductive fibers, processes for manufacturing this film and use of this film in heat transfer joints.

U.S. Patent 6,364,009 to MacManus et al., "Cooling Devices," discloses a cooling apparatus for cooling an electrical device using a flow of coolant comprising a cooling unit.

European Patent Application EP 0 506 509 A to Sono et al., "Semiconductor Device Having Radiation Part and Method of Producing the Same," discusses a semiconductor device having a radiation part for radiating heat and a method of producing such a semiconductor device.

International Patent Publication WO 03/017365 A to Flint et al., "Thermal Transfer Devices," discloses thermal transfer devices, including heat pipes and vapor chambers.

U.S. Patent 6,397,941 to McCullough, "Net-shape Molded Heat Exchanger," discloses apparatuses for dissipating heat generated by such objects.

INT-03-008

European Patent Application EP 1 265 281 A to Tobita et al., "Thermally Conductive Molded Article and Method of Making the Same," discloses a thermally conductive molded article that has excellent thermal conductivity and a method of making the same.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the typed name.

Stephen B. Ackerman,  
Reg. No. 37761

~~SECRET~~ TO-1449

<p> <b>Doctor Number (Optional)</b>                  _____             </p>
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Application Number

INT-03-008

10 | 807,036

Applicant:

Thomas Aisenbrey

Filing Date

3/23/04

Group Art Unit

INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION

(Use several sheets if necessary)

## U. S. PATENT DOCUMENTS

[illegible]

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER						DATE	COUNTRY	CLASS	SUBCLASS	Translation	
	YES	NO										
EP 0 50 6 50 9 A	3/16/92	European Patent App.	H 01 L	23/055								
WO 03 / 01 736 5 A	8/17/01	Int'l Patent	H 01 L	23/34								
EP 1 265 281 A	6/5/02	European Patent App.	H 01 L	23/373								

OTHER DOCUMENTS (Including Author, Title, Date, Portion, Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.